STD80N6F6



Automotive-grade N-channel 60 V, 4.4 mΩ typ., 80 A STripFET™ VI DeepGATE™ Power MOSFET in a DPAK package

Datasheet - production data

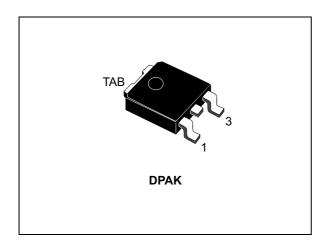
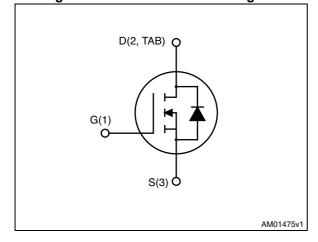


Figure 1. Internal schematic diagram



Features

Order code	V _{DS}	R _{DS(on)} max.	I _D
STD80N6F6	60 V	5 mΩ	80 A ⁽¹⁾

- 1. Current limited by package
- Designed for automotive applications and AEC-Q101 qualified
- · Low gate charge
- · Very low on-resistance
- High avalanche ruggedness

Applications

Switching applications

Description

This device is an N-channel Power MOSFET developed using the 6^{th} generation of STripFET™ DeepGATE™ technology, with a new gate structure. The resulting Power MOSFET exhibits the lowest $R_{DS(on)}$ in all packages.

Table 1. Device summary

Order code	Marking	Packages	Packaging
STD80N6F6	80N6F6	DPAK	Tape and reel

Contents STD80N6F6

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STD80N6F6 Electrical ratings

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit	
V _{DS}	Drain-source voltage	60	V	
V _{GS}	Gate-source voltage	± 20	V	
I _D ⁽¹⁾	Drain current (continuous) at T _C = 25 °C	80	Α	
I _D ⁽¹⁾	Drain current (continuous) at T _C = 100 °C	80	Α	
I _{DM} ⁽¹⁾	Drain current (pulsed)	320	Α	
P _{TOT}	Total dissipation at T _C = 25 °C	120	W	
	Derating factor	0.8	W/°C	
T _{stg}	Storage temperature	55 to 175	°C	
T _j	Operating junction temperature	- 55 to 175		

^{1.} Current limited by package

Table 3. Thermal data

Symbol	Parameter	Value	Unit
R _{thj-case}	Thermal resistance junction-case max	1.25	°C/W
R _{thj-a}	Thermal resistance junction-ambient max	50	°C/W

Electrical characteristics STD80N6F6

2 Electrical characteristics

(T_{CASE} = 25 °C unless otherwise specified)

Table 4. On/off states

Symbol	Parameter Test conditions Min.		Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage (V _{GS} = 0)	I _D = 250 μA	60			V
Zero gate voltage		V _{DS} = 60 V			1	μΑ
I _{DSS}	Drain current (V _{GS} = 0)	V _{DS} = 60 V, T _C =125 °C			100	μΑ
I _{GSS}	Gate-body leakage current (V _{DS} = 0)	V _{GS} = ± 20 V			± 100	nA
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	3		4.5	V
R _{DS(on)}	Static drain-source on-resistance	V _{GS} = 10 V, I _D = 40 A		4.4	5	mΩ

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C _{iss}	Input capacitance		-	8325	-	pF
C _{oss}	Output capacitance	$V_{DS} = 25 \text{ V, f} = 1 \text{ MHz,}$	-	500	-	pF
C _{rss}	Reverse transfer capacitance	$V_{GS} = 0$	-	400	-	pF
Q_g	Total gate charge	V 00 V I 00 A	-	147	-	nC
Q _{gs}	Gate-source charge	$V_{DD} = 30 \text{ V}, I_{D} = 80 \text{ A},$ $V_{GS} = 10 \text{ V}$	-	44	-	nC
Q_{gd}	Gate-drain charge	- GS - 10 - 1	-	46	-	nC

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)}	Turn-on delay time		-	40	-	ns
t _r	Rise time	V _{DD} = 30 V, I _D = 40 A	-	71	-	ns
t _{d(off)}	Turn-off-delay time	$R_{G} = 4.7 \Omega V_{GS} = 10 V$	-	132	-	ns
t _f	Fall time		-	40	-	ns



Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Тур.	Max	Unit
I _{SD}	Source-drain current		-		80	Α
I _{SDM} ⁽¹⁾	Source-drain current (pulsed)		-		320	Α
V _{SD} (2)	Forward on voltage	I _{SD} = 80 A, V _{GS} = 0	-		1.3	٧
t _{rr}	Reverse recovery time $I_{SD} = 80 \text{ A}, V_{DD}$		-	46		ns
Q _{rr}	Reverse recovery charge	$di/dt = 100 A/\mu s$,	-	65		nC
I _{RRM}	Reverse recovery current	T _j = 150 °C	1	2.8		Α

^{1.} Current limited by package.

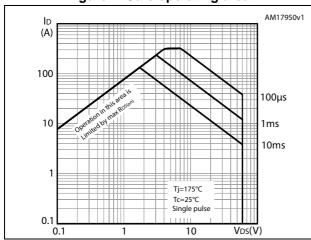
^{2.} Pulsed: pulse duration = 300 μ s, duty cycle 1.5%

Electrical characteristics STD80N6F6

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

Figure 3. Thermal impedance



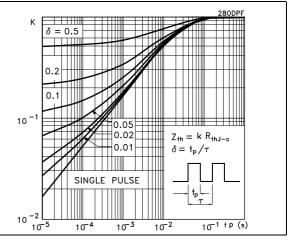
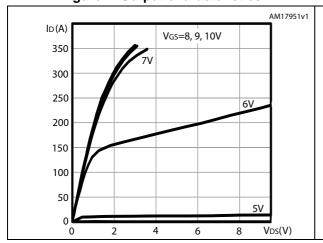


Figure 4. Output characteristics

Figure 5. Transfer characteristics



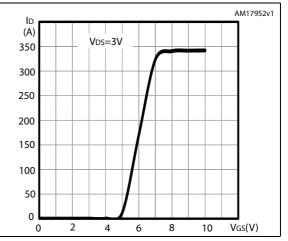
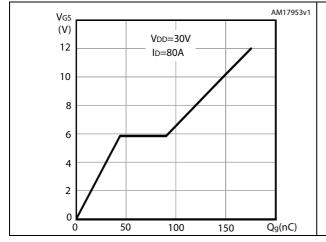
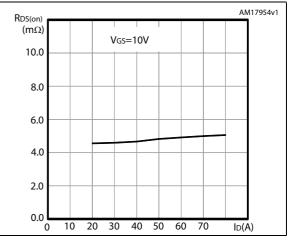


Figure 6. Gate charge vs gate-source voltage

Figure 7. Static drain-source on-resistance



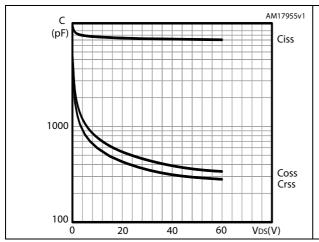


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Figure 8. Capacitance variations

Figure 9. Normalized gate threshold voltage vs temperature



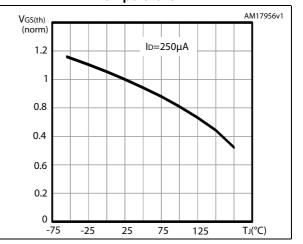
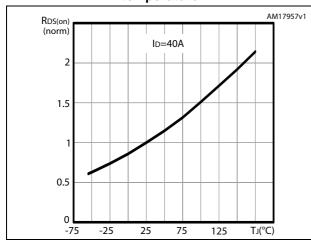


Figure 10. Normalized on-resistance vs temperature

Figure 11. Normalized $\ensuremath{V_{DS}}$ vs temperature



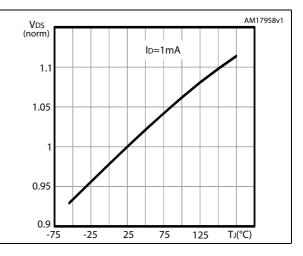
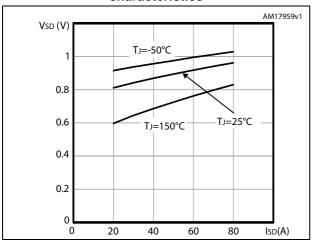


Figure 12. Source-drain diode forward characteristics



3 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.



E -THERMAL PAD c2 *L2* D1 Н <u>b(</u>2x) R C SEATING PLANE (L1) *V2* GAUGE PLANE 0,25 0068772_K_type_A

Figure 13. DPAK (TO-252) type A drawing

Table 8. DPAK (TO-252) type A mechanical data

Di		mm	
Dim.	Min.	Тур.	Max.
Α	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
С	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1		5.10	
E	6.40		6.60
E1		4.70	
е		2.28	
e1	4.40		4.60
Н	9.35		10.10
L	1.00		1.50
(L1)		2.80	
L2		0.80	
L4	0.60		1.00
R		0.20	
V2	0°		8°

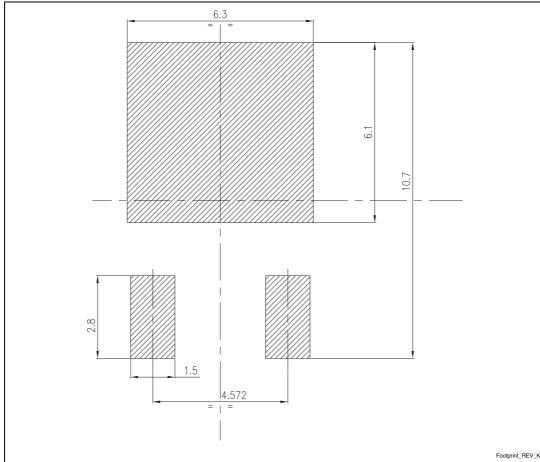


Figure 14. DPAK footprint (a)

a. All dimensions are in millimeters



4 Packaging mechanical data

10 pitches cumulative tolerance on tape +/- 0.2 mm

Top cover power powe

Figure 15. Tape for DPAK (TO-252)

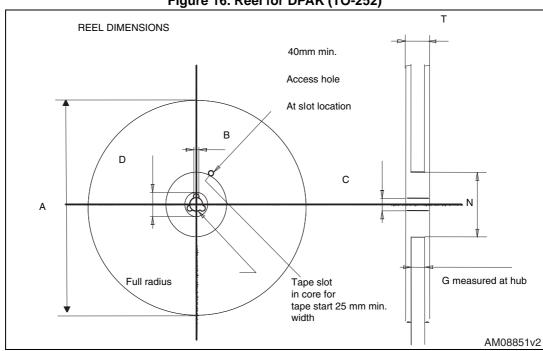


Figure 16. Reel for DPAK (TO-252)

Table 9. DPAK (TO-252) tape and reel mechanical data

	Таре	,		Reel		
Dim	mm		Dim.	mm		
Dim.	Min.	Max.		Min.	Max.	
A0	6.8	7	А		330	
В0	10.4	10.6	В	1.5		
B1		12.1	С	12.8	13.2	
D	1.5	1.6	D	20.2		
D1	1.5		G	16.4	18.4	
Е	1.65	1.85	N	50		
F	7.4	7.6	Т		22.4	
K0	2.55	2.75			•	
P0	3.9	4.1		Base qty.	2500	
P1	7.9	8.1		Bulk qty.	2500	
P2	1.9	2.1				
R	40					
Т	0.25	0.35				
W	15.7	16.3				

Revision history STD80N6F6

5 Revision history

Table 10. Document revision history

Date	Revision	Changes
08-Aug-2012	1	Initial release.
17-Jan-2014	2	 Document status promoted from preliminary to production data Modified: title Modified: Features Added: note 1 in cover page Modified: R_{DS(on)max} and I_D values in cover page Modified: Derating factor value in Table 2 Modified: R_{DS(on)} values in Table 4 Modified: I_D and the entire typical values in Table 5, 6 and 7 Added: Section 2.1: Electrical characteristics (curves) Updated: Section 3: Package mechanical data Minor text changes

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